

AMENDMENTS TO THE CLAIMS

Claims 1-17 (Canceled)

Claim 18 (Withdrawn) A method for producing a substrate holder for holding a circuit board, comprising the steps of:

placing an adhesive material on a main body to become the substrate holder; and
pressing a mold against the adhesive material while heating the mold, the mold having an undulating pattern for tackiness adjustment provided thereon.

Claim 19 (Withdrawn) The method according to claim 18, wherein
the mold includes a region in which a first undulating pattern is formed and a region in which a second undulating pattern is formed.

Claim 20 (Withdrawn) The method according to claim 19, wherein,
the mold is differentiated in level between the region in which the first undulating pattern is formed and the region in which the second undulating pattern is formed.

Claim 21 (Withdrawn) A method for producing a mold to be used for forming an undulating pattern for tackiness adjustment on an adhesive material of a substrate holder for holding a circuit board, comprising the steps of:

forming a pressing surface of the mold; and
blasting minute particles against the pressing surface.

Claim 22 (Withdrawn) The method according to claim 21, further comprising, before the step of blasting minute particles:

a step of placing a mask so as to oppose the pressing surface.

Claim 23 (Withdrawn) The method according to claim 21, further comprising, after the step of blasting minute particles:

a step of placing a mask so as to oppose the pressing surface; and
blasting another type of minute particles against the pressing surface through the mask.

Claim 24 (Withdrawn) A method for producing a mold to be used for forming an undulating pattern for tackiness adjustment on an adhesive material of a substrate holder for holding a circuit board, comprising the steps of:

forming a pressing surface of the mold; and
forming an undulating pattern on the pressing surface by chemical etching.

Claims 25-26 (Canceled)

Claim 27 (New) A substrate holder for holding a circuit board, comprising:

a main body; and
a holding surface formed on the main body for allowing a circuit board to adhere to the holding surface, wherein the holding surface includes:
a first adhesive holding region for holding the circuit board with a first tackiness; and
a second adhesive holding region for holding the circuit board with a second tackiness which is different from the first tackiness, said first and second adhesive holding regions not overlapping each other and being capable of holding the circuit board in cooperation;
wherein the first adhesive holding region and the second adhesive holding region are arranged parallel to the surface of said main body.

Claim 28 (New) The substrate holder of claim 27, and further comprising an adhesive material provided on said main body, said first adhesive holding region and said second adhesive holding region being on a surface of said adhesive material.

Claim 29 (New) The substrate holder of claim 28, wherein the first adhesive holding region and the second adhesive holding region are within one area of the adhesive material on said main body.

Claim 30 (New) The substrate holder of claim 29, wherein the first adhesive holding region and the second adhesive holding region are composed of the same adhesive material, and the first adhesive holding region and the second adhesive holding region have different surface undulation characteristics.

Claim 31 (New) The substrate holder of claim 30, wherein the first adhesive holding region and the second adhesive holding region have different surface coarseness.

Claim 32 (New) The substrate holder of claim 28, wherein the first adhesive holding region and the second adhesive holding region are composed of the same adhesive material, and the first adhesive holding region and the second adhesive holding region have different surface undulation characteristics.

Claim 33 (New) The substrate holder of claim 32, wherein the first adhesive holding region and the second adhesive holding region have different surface coarseness.

Claim 34 (New) The substrate holder of claim 27, wherein the first adhesive holding region and the second adhesive holding region are within one plane.

Claim 35 (New/Withdrawn) The substrate holder of claim 27, wherein the first adhesive holding region and the second adhesive holding region are differentiated in level.

Claim 36 (New/Withdrawn) The substrate holder of claim 35, wherein one of the first and second adhesive holding regions surrounds the other of the first and second adhesive holding

regions, and the other of the first and second adhesive holding regions projects from the one of the first and second adhesive holding regions.

Claim 37 (New/Withdrawn) The substrate holder of claim 36, wherein one of the first and second adhesive holding regions surrounds a bottom of a depression comprising the other of the first and second adhesive holding regions.

Claim 38 (New) The substrate holder of claim 27, wherein the first tackiness is less than the second tackiness and the second adhesive holding region is confined within the first adhesive holding region.

Claim 39 (New) The substrate holder of claim 27, wherein the first tackiness is less than the second tackiness and a through hole for receiving a pin is in the first adhesive region, the through hole being usable by the pin for peeling off the circuit board.

Claim 40 (New) The substrate holder of claim 39, wherein an air outlet is provided in the second adhesive region.

Claim 41 (New/Withdrawn) The substrate holder of claim 29, wherein the first tackiness is less than the second tackiness and the first adhesive holding region is confined within the second adhesive holding region.

Claim 42 (New) The substrate holder of claim 27, wherein the holding surface comprises a plurality of sets of the first adhesive holding region and the second adhesive holding region.

Claim 43 (New) The substrate holder of claim 28, wherein the adhesive material comprises silicone rubber, polyurethane rubber or fluorine rubber.

Claim 44 (New) A pallet for carrying a circuit board comprising:

a main body; and

a holding surface formed on the main body for allowing a circuit board to adhere to the holding surface, wherein the holding surface includes:

a first adhesive holding region for holding the circuit board with a first tackiness; and

a second adhesive holding region for holding the circuit board with a second tackiness which is different from the first tackiness, said first and second adhesive regions not overlapping each other and being capable of holding the circuit board in cooperation;

wherein the first adhesive holding region and the second adhesive holding region are arranged parallel to the surface of said main body.